

3ni31

Bni31 Feature

UNIT size	600(W)x600(D)X680(H)mm (except Display)
Rotation of Plate	10 ~ 150 rpm
Diameter of Plate	300mm
Applied Jig	Up to 3 inch jig
Sweep arm	1 arm
Slurry feeding	Auto mixing and feeding(option)
Timer	Max 99Hour 59Minutes
Operation	Touch panel control
Net weight	60kg(including cover, polishing plate)
Power Supply	100V/240V
Consumption current	8.5A/5A

Precision Materials Processing

3ni BN TECHNOLOGY CORPORATION
A MEMBER OF BN INTERNATIONAL GROUP

BN Technology Corporation

Head office

Level 5, Pacific Marks Shinjuku Parkside
4-15-7 Nishi-Shinjuku, Shinjuku-ku, Tokyo
160-0023, Japan
TEL:+81-3-5365-2551 FAX:+81-3-5365-3900
E-mail: info@bn-technology.co.jp
URL: www.bn-technology.co.jp

Technical Center

3-1-2 Osawa, Mitaka, Tokyo 181-0015, Japan
TEL:+81-42-230-5440 FAX:+81-42-230-5441



Extreme precise Lapping/Polishing Machine

Achieve extreme precise polishing under nano-technology environment



Leading edge LSI PROCESS. Extreme precise DELAYERING BACK SIDE POLISHING for SIL analysis



Bni31 System Feature

Optimum system

Offer not only hardware but also optimum system as package including technology and know-how up to 3" wafer.

Capability for research laboratories up to small volume production.

Bni31 covers extreme precise lapping and polishing with itself and can be used for research laboratories up to small volume production.

Accuracy

Bni31 achieved extreme high accuracy that is required in nano-technology material area.

Extreme precise CMP

Offer most optimum system under the condition that is required in planarization, uniformity of thickness.

Lapping/Polishing

BN offers best surface finish with unique and extremely precise jig and plate based on the advanced technology of CMP etc.

Easy operation

All function, rotation of plate and slurry auto feed etc. can be controlled with touch panel on 5.4 inch LCD panel.

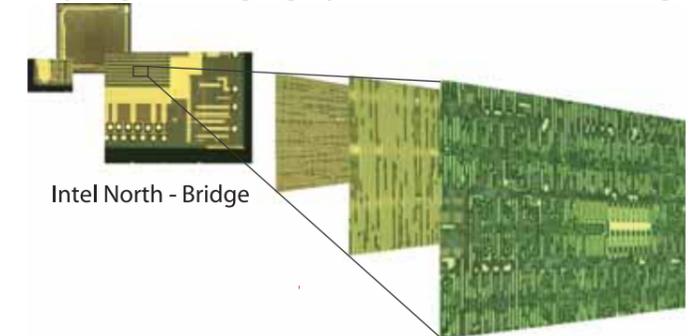


Application

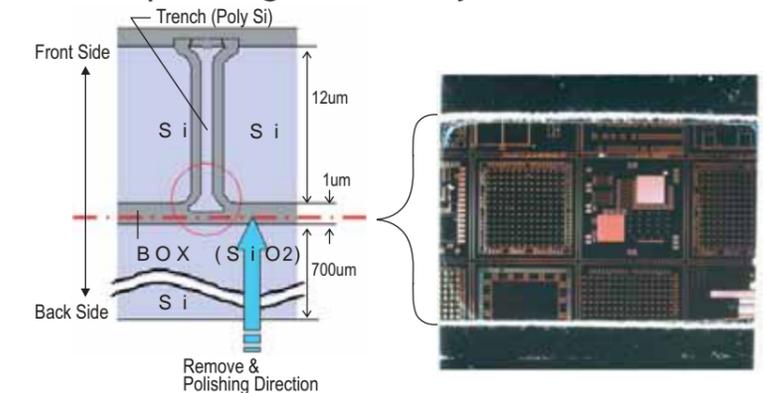
Failure analysis/delayering

Capable for delayering,peeling off layer by one layer extreme precisely. With delayering know-how of BN,offer polishing solution that essential to failure analysis, Extreme precise delayering with Bni31 shorten the process of failure analysis.

Delayering for leading edge system LSI(available for Cu wiring)



Back side polishing for SIL analysis



Polishing jig

Support samples firmly control the pressure to the work, Jig can be customized with request. Bni31 can be applied for various application.

3-inch Jig



Sample load Scale

Jig attachment



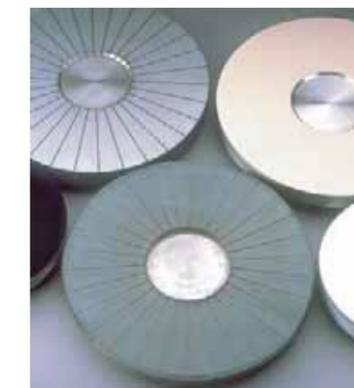
Provide various attachment for Vacuum chuck, section polishing, fiber etc.

Polishing slurry

Offer optimum solution that is suitable to user's application with various polishing materials, lapping powder to CMP slurry.

Polishing plate

Offer optimum polishing plate that is suitable for user's works and objects.



Provide various plate

- Cast iron
- Tin
- Plate for polishing cloth
- Glass
- Polyurethane

Provide optimum plate, other material, trench that is requested from users.